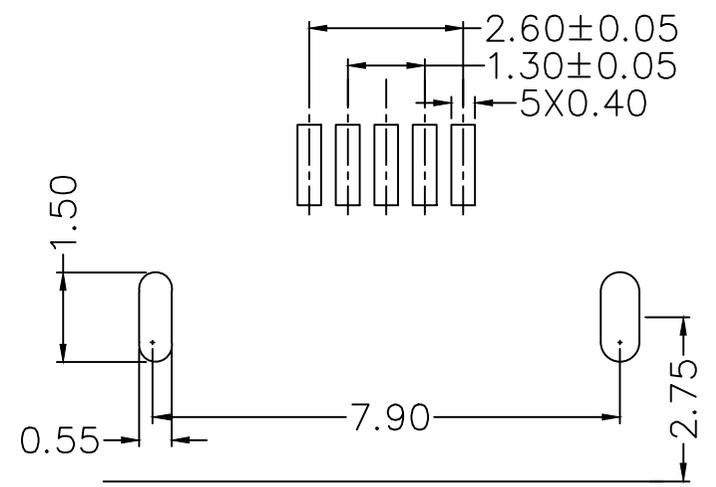
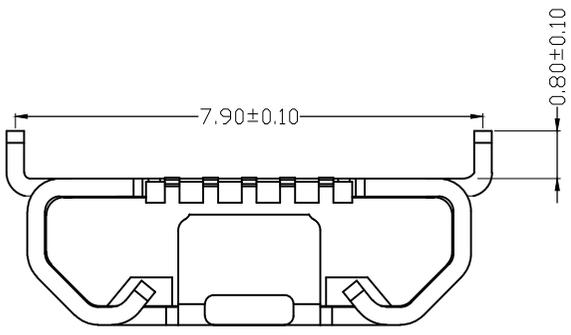
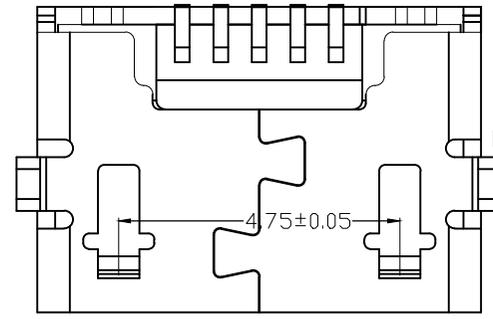
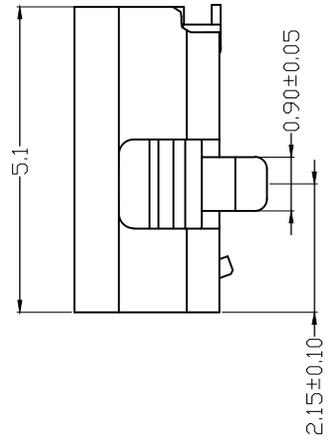
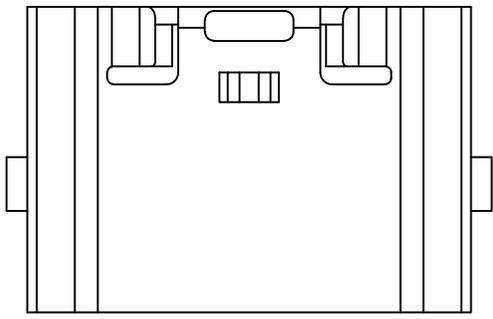


REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2011/10/31

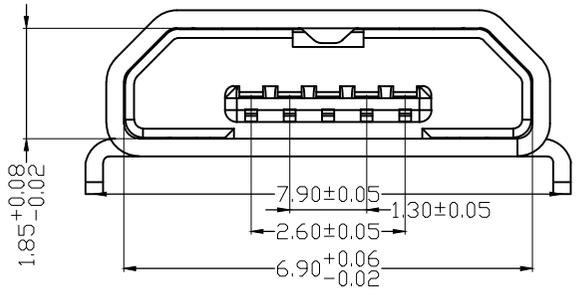


PCB LAYOUT



Note:

- 1.Material:
 - 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
 - 1.2 Contact: copper alloy,t=0.15mm
 - 1.3 Shell: copper alloy&SUS
- 2.Specification:
 - 2.1 Current rating: 1 A Max.
 - 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
 - 2.3 Contact resistance: 30 mΩ Max.
 - 2.4 Insulation resistance: 100 MΩ Min.
 - 2.5 Total mating force: 3.57 Kgf Max.
 - 2.6 Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.after 10000 insertion/extraction cycles
 - 2.7 Temperature range: -30°C~80°C



GENERAL TOLERANCE		DWG NO.	JYSA1014-03	APPD:	WIND	Scale	1:1
X.±0.45	x.'±5'	Title	MICRO 5P/F B 反向两脚DIP 7.9mm 无柱直边	CHKD:		UNIT	mm
.X±0.35	.x'±2'			DR:			
.XX±0.25	.xx'±1'	Part NO.	JYS-USB790-078	Date	2011/10/31		
.XXX±0.15	.xxx'±0.5'			Shenzhen JYSCONN Electronics Co., LTD.			
SHEET	1/1						